What is claimed is:

1.   A method for analysing connection conditions between
     an integrated circuit package and a circuit board,
5   -   wherein said integrated circuit package is
         electrically coupled to said circuit board by coupling
         elements, and
     -   wherein said integrated circuit package is
         mechanically connected with said circuit board by
10   support elements,
         characterised in that
     -   physical values are picked-off from said support
         elements, and
     -   said physical values are evaluated to determine the
15   condition of said connection between said integrated
         circuit package and said circuit board.

2.   The method of claim 1, wherein electrical values are
     picked-off from said support elements.

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3.   The method of claim 1, wherein electrical resistance
     and/or electrical current and/or voltage within said
     support elements is picked-off.

25 4.   The method of claim 1, wherein mechanical values are
     picked-off from said support elements.

5.   The method of claim 1, wherein mechanical values are
     picked-off from said support elements using a strain
30   gauge.

6.   The method of claim 1, wherein a condition of said
     electrical coupling of said integrated circuit package

with said circuit board is concluded from said determined condition of said connection.

7. The method of claim 1, wherein said connection condition is determined in intervals.

8. The method of claim 1, wherein said determined connection conditions are stored.

9. The method of claim 1, wherein in case a poor connection condition is determined, a error message is generated.

10. The method of claim 9, wherein said error message is presented on a user interface.

11. The method of claim 9, wherein said error message is stored.

12. The method of claim 9, wherein said error message is read out from a storage and used for maintenance.

13. A system for analysing connection conditions between an integrated circuit package and a circuit board, comprising:
    -   coupling elements coupling said integrated circuit package electrically to said circuit board, and
    -   support elements connecting said integrated circuit package mechanically with said circuit board, characterised by
    -   measuring means arranged at said support elements to pick-off physical values from said support elements, and
    -   evaluation means evaluating said physical values to determine the condition of said connection between

said integrated circuit package and said circuit
board.

14. The system of claim 13, wherein said support elements
are arranged between said circuit board and said
integrated circuit package.

15. The system of claim 13, wherein said support elements
are solder pads.

16. The system of claim 13, wherein said support elements
are arranged adjacent to said coupling elements.

17. The system of claim 13, wherein said support elements
are arranged semicircular along said coupling
elements.

18. The system of claim 13, wherein said support elements
are arranged along edges and/or at corners of said
integrated circuit package.

19. The system of claim 13, wherein said integrated
circuit package is a chip scale package or a chip size
package.

20. The system of claim 13, wherein said measuring means
provide picking-off electrical conditions of said
support elements.

21. The system of claim 13, wherein said measuring means
provide picking-off mechanical conditions of said
support elements.

22. The system of claim 13, wherein storage means are
comprised to store said picked-off physical values.

23. The system of claim 13, wherein said evaluation means compare said picked-off physical values with comparative values to determine the connection condition.

24. The system of claim 13, wherein said evaluation means provide an error message in case a poor connection condition is determined.

25. The system of claim 13, wherein said error message is stored within said storage means.

26. The system of claim 13, wherein an interface is provided to read out said stored physical values and/or stored error messages.

27. A consumer electronic device, in particular a mobile phone, comprising a system of claim 13.

28. A computer program operable to cause a processor to analyse connection conditions between an integrated circuit package and a circuit board according to a method of claim 1.

29. A computer program product comprising a computer program operable to cause a processor to analyse connection conditions between an integrated circuit package and a circuit board according to a method of claim 1.